

# **Micro-Stereolithography: Physics and Technologies**

Xiang Zhang

Department of Mechanical and Aerospace Engineering  
University of California, Los Angeles

REPORT DOCUMENTATION PAGE				Form Approved OMB No. 0704-0188	
Public reporting burden for this collection of information is estimated to average 1 hour per response, including the time for reviewing instructions, searching existing data sources, gathering and maintaining the data needed, and completing and reviewing this collection of information. Send comments regarding this burden estimate or any other aspect of this collection of information, including suggestions for reducing this burden to Department of Defense, Washington Headquarters Services, Directorate for Information Operations and Reports (0704-0188), 1215 Jefferson Davis Highway, Suite 1204, Arlington, VA 22202-4302. Respondents should be aware that notwithstanding any other provision of law, no person shall be subject to any penalty for failing to comply with a collection of information if it does not display a currently valid OMB control number. PLEASE DO NOT RETURN YOUR FORM TO THE ABOVE ADDRESS.					
1. REPORT DATE (DD-MM-YYYY) 30-05-2001		2. REPORT TYPE Workshop Presentations		3. DATES COVERED (FROM - TO) 30-05-2001 to 01-06-2001	
4. TITLE AND SUBTITLE Micro-Stereolithography: Physics and Technologies Unclassified				5a. CONTRACT NUMBER	
				5b. GRANT NUMBER	
				5c. PROGRAM ELEMENT NUMBER	
6. AUTHOR(S) Zhang, Xiang ;				5d. PROJECT NUMBER	
				5e. TASK NUMBER	
				5f. WORK UNIT NUMBER	
7. PERFORMING ORGANIZATION NAME AND ADDRESS Department of Mechanical and Aerospace Engineering University of California, Los Angeles Los Angeles, CAxxxxx				8. PERFORMING ORGANIZATION REPORT NUMBER	
9. SPONSORING/MONITORING AGENCY NAME AND ADDRESS Office of Naval Research International Field Office Office of Naval Research Washington, DCxxxxx				10. SPONSOR/MONITOR'S ACRONYM(S)	
				11. SPONSOR/MONITOR'S REPORT NUMBER(S)	
12. DISTRIBUTION/AVAILABILITY STATEMENT A PUBLIC RELEASE					
13. SUPPLEMENTARY NOTES See Also ADM001348, Thermal Materials Workshop 2001, held in Cambridge, UK on May 30-June 1, 2001. Additional papers can be downloaded from: <a href="http://www-mech.eng.cam.ac.uk/onr/">http://www-mech.eng.cam.ac.uk/onr/</a>					
14. ABSTRACT ? mSL principles and apparatus design ? Prototyping of polymeric and ceramic microstructures ? Experiment and modeling					
15. SUBJECT TERMS					
16. SECURITY CLASSIFICATION OF:		17. LIMITATION OF ABSTRACT Public Release	18. NUMBER OF PAGES 23	19. NAME OF RESPONSIBLE PERSON Fenster, Lynn lfenster@dtic.mil	
a. REPORT Unclassified	b. ABSTRACT Unclassified	c. THIS PAGE Unclassified		19b. TELEPHONE NUMBER International Area Code Area Code Telephone Number 703767-9007 DSN 427-9007	
				Standard Form 298 (Rev. 8-98) Prescribed by ANSI Std Z39.18	

## Acknowledgement:

Students at my group:

Cheng Sun, Nick Fang, Xiaoning Jiang, Ming Xi,  
Dongmin Wu, Zhiliang Wan

NSF CAREER award

ONR Young Investigator Award

# Outline

- Introduction
- Micro-Stereolithography ( $\mu$ SL)
  - $\mu$ SL principles and apparatus design
  - Prototyping of polymeric and ceramic microstructures
  - Experiment and modeling
- Applications

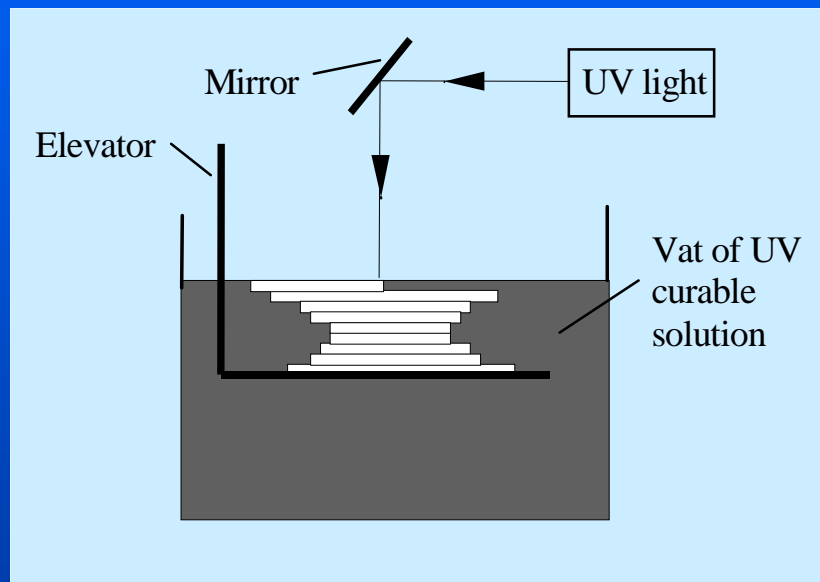


# Background

- Future high Performance MEMS requires:
  - 3D complex micro-structures
  - Incorporating with a broader spectrum of materials (Smart materials, functional polymer, and magnetic alloys)
- However, current silicon IC fabrication can not provide an effective solution.
- Other efforts:
  - X-ray LIGA: high aspect ratio 2.5D, but not true 3D
  - Micro-mechanical machining: complex 3D, but very slow and severe tool wear
  - EFAB, 3D, need many masks needed and limited to metal

# A New Approach— Scale Down Rapid Prototyping Technologies

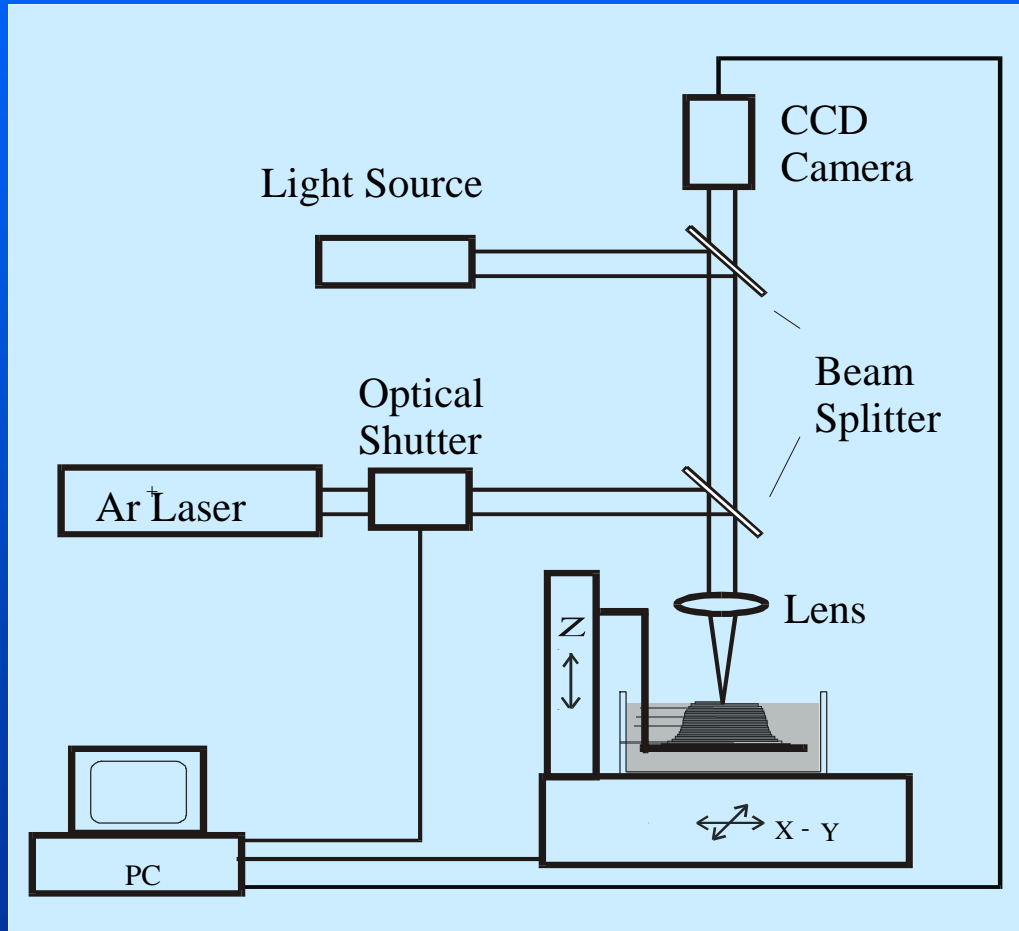
## Micro-Stereolithography



(Ikuta, 1996)

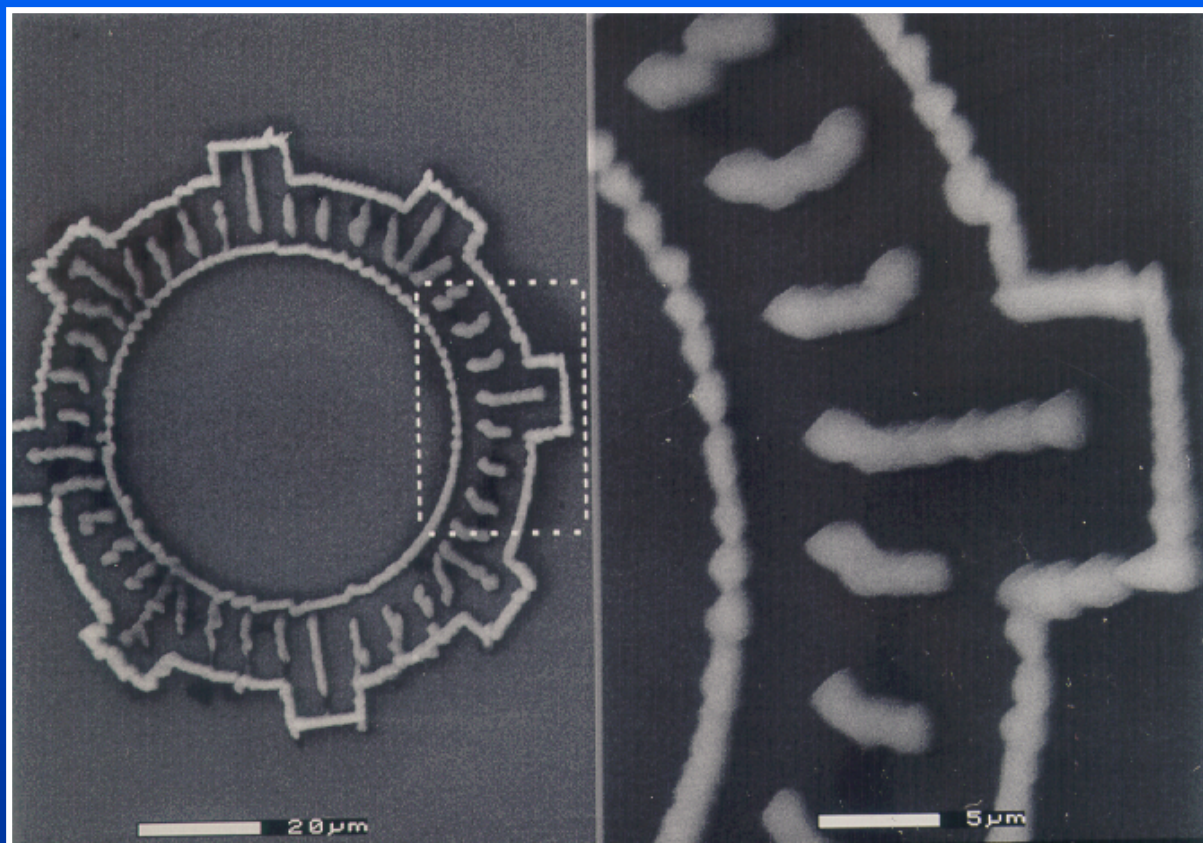
- UV laser micro photo-forming of 3D complex micro-parts
- A layer-by-layer additive process
- CAD design capability
- Incorporation of many functional materials

# An Advanced Micro-Stereolithography Apparatus



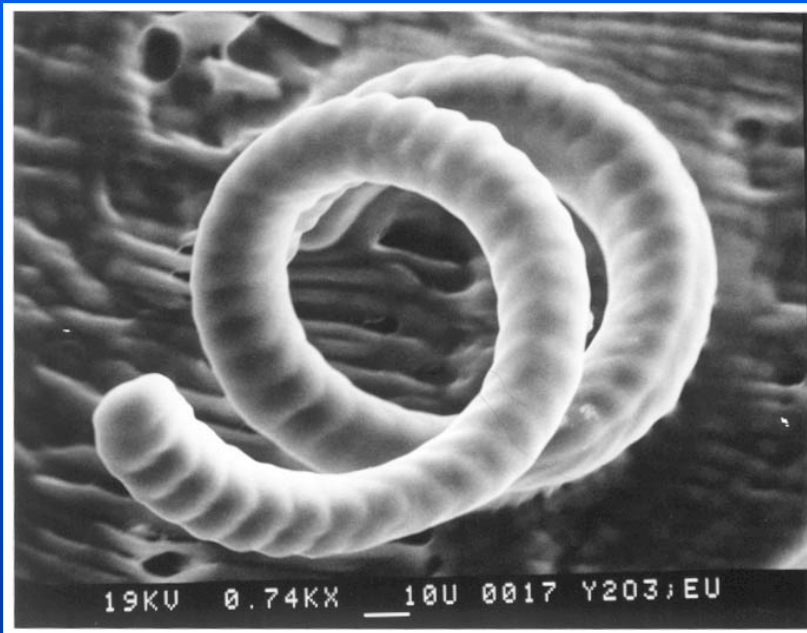
- Laser:  $\lambda=364$  nm
- X-Y-Z stepper resolution:  $0.5\ \mu\text{m}$
- UV beam spot:  $1\ \mu\text{m}$

## Test Pattern with 2 $\mu\text{m}$ Line Width

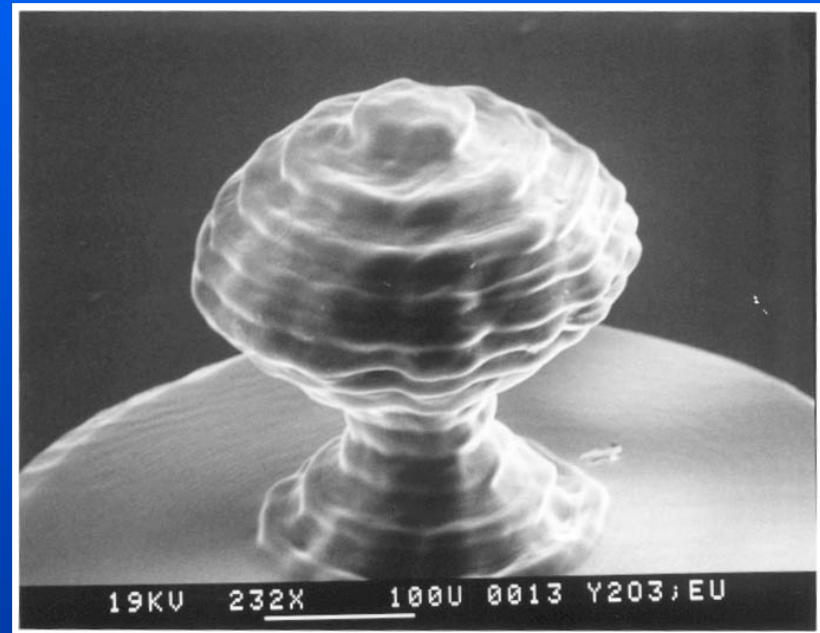


# Micro-Stereolithography of 3D Complex Structures

- Micro-spring



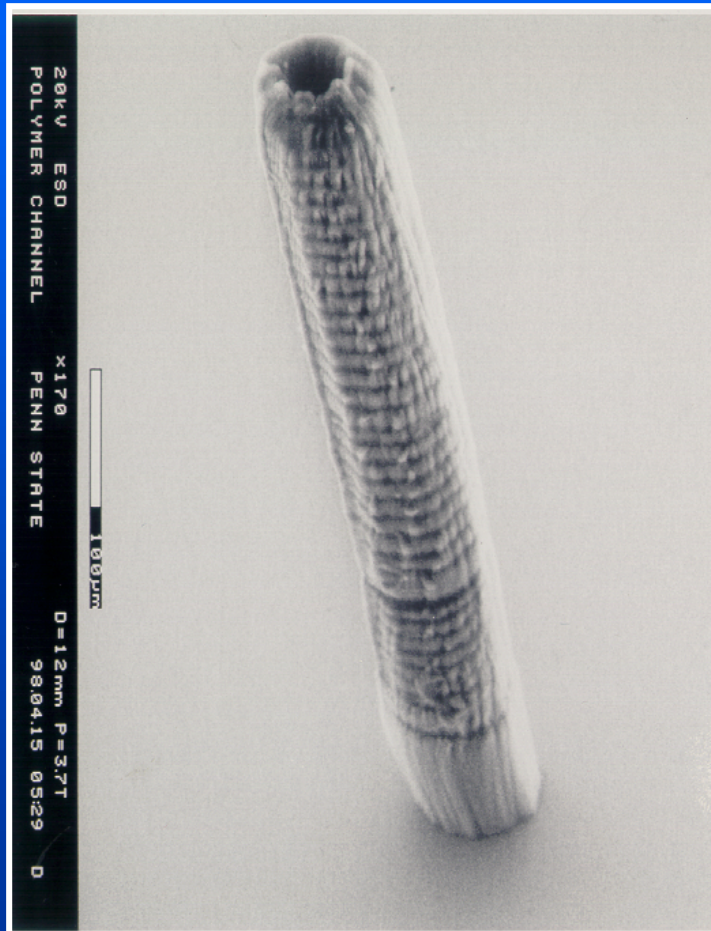
- Micro-mushroom





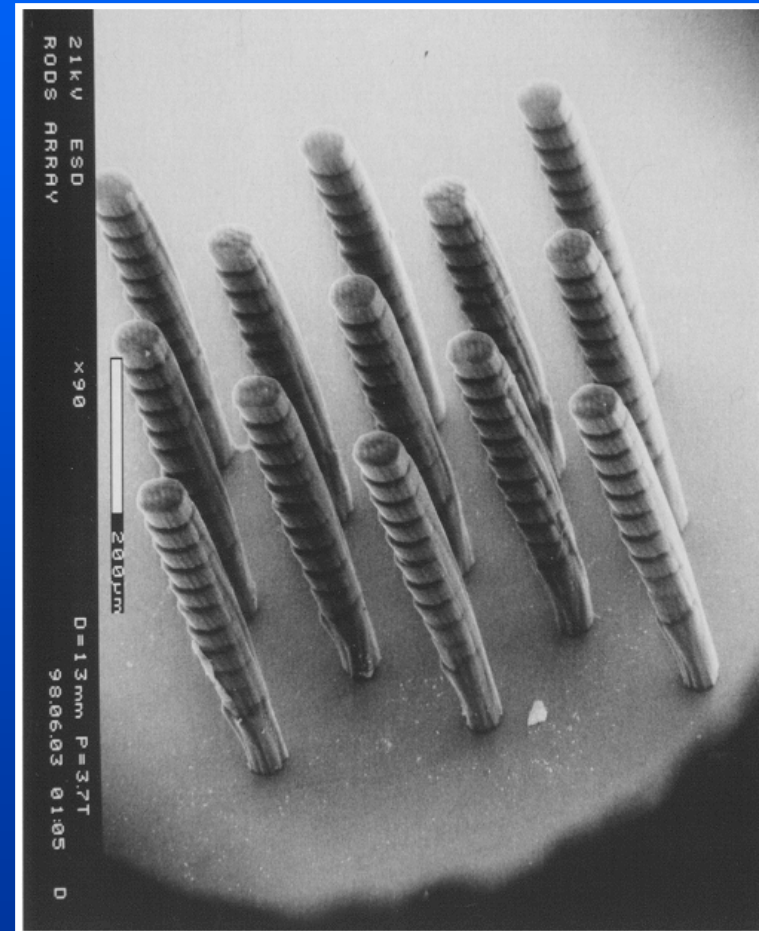
- **Micro-tube**

(50  $\mu\text{m}$  inner diameter and 800  $\mu\text{m}$  long)



- **Micro-rod Array**

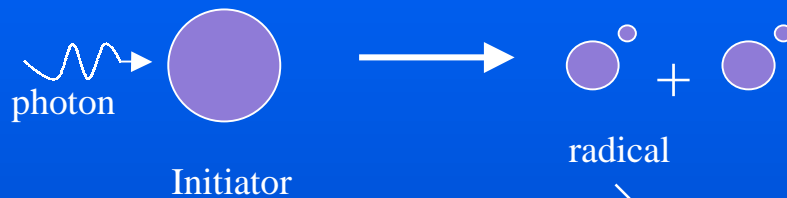
(50  $\mu\text{m}$  diameter and 500  $\mu\text{m}$  long)



# Simulation of Micro-Stereolithography of Polymer

## Photopolymerization

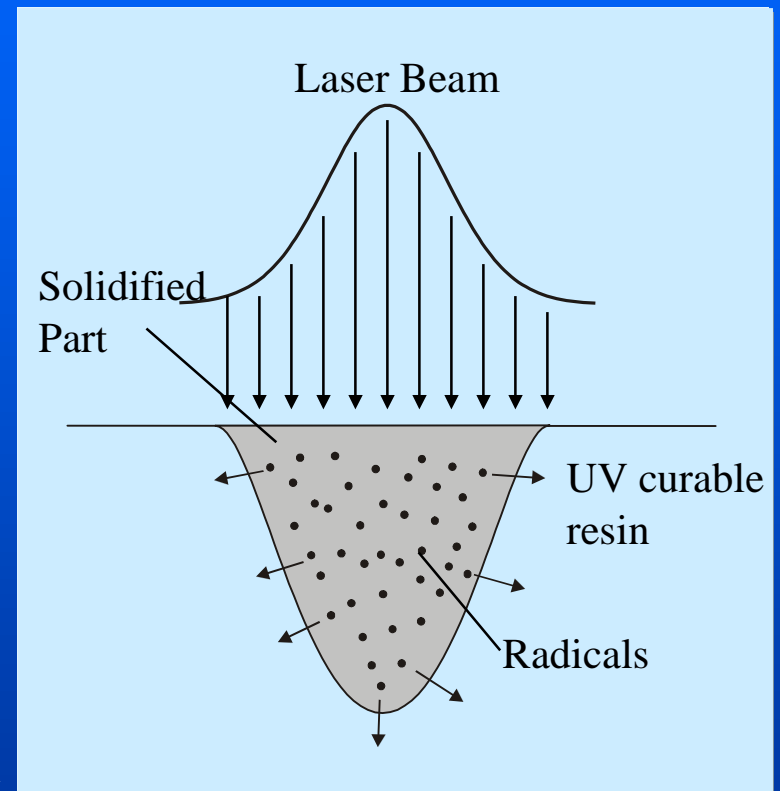
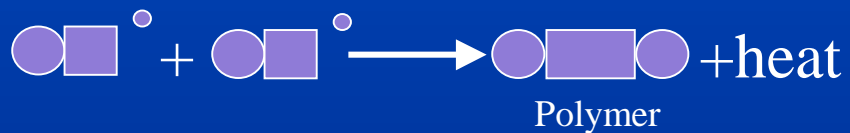
- **Initiation:**



- **Propagation:**



- **Termination:**



# Simulation Approach

- **Light absorption:**

$$\frac{dI}{dz} = -\epsilon [S] I$$

- **Photoinitiation:**

$$\frac{d[S]}{dt} = -\psi \epsilon [S] I$$

- **Diffusion of Radicals:**

$$\frac{d[R]}{dt} = D \left[ \frac{1}{r} \frac{\partial}{\partial r} \left( r \frac{\partial [R]}{\partial r} \right) + \frac{\partial^2 [R]}{\partial z^2} \right] + \phi \epsilon [S] I - k_t [R]^2$$

- **Polymerization Kinetics:**

$$\frac{d[M]}{dt} = -k_p [R] [M]$$

- **Heat Transfer:**

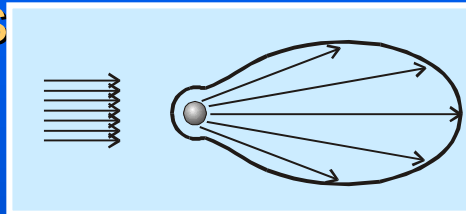
$$\rho C_p \frac{\partial T}{\partial t} = k \left[ \frac{1}{r} \frac{\partial}{\partial r} \left( r \frac{\partial T}{\partial r} \right) + \frac{\partial^2 T}{\partial z^2} \right] - k_p [R] [M] \Delta H$$



# Monte-Carlo Simulation of $\mu$ SL of Ceramics

## Single photon tracing processes

- Scattering
  - Mie theory

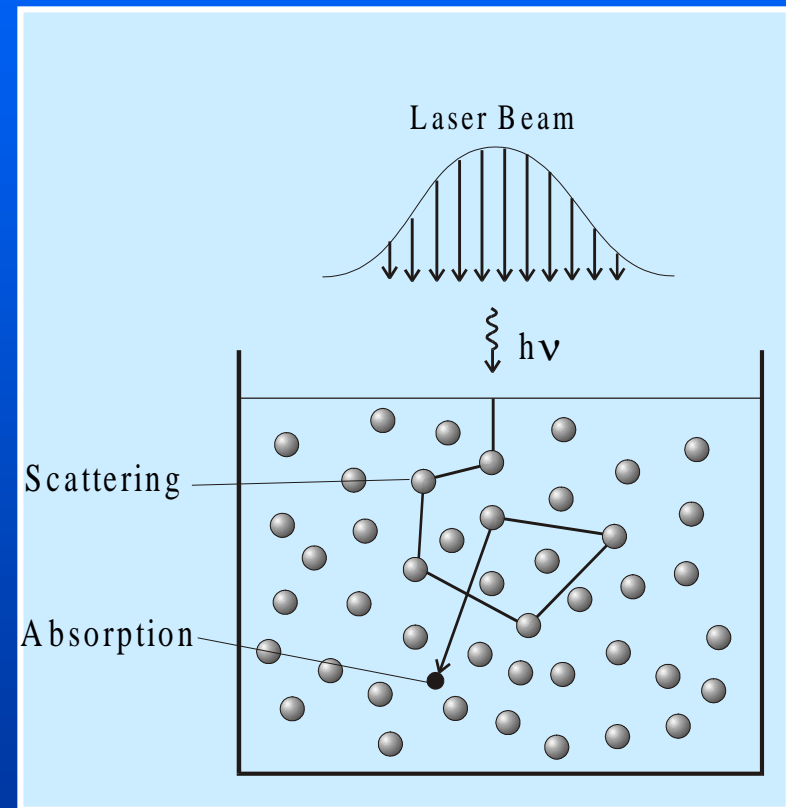


- Absorption during traveling
  - travel:
  - absorption:

$$P = e^{-l/\lambda}, \lambda = \frac{4 \cdot r}{3 \cdot s} \text{ (MFP)}$$

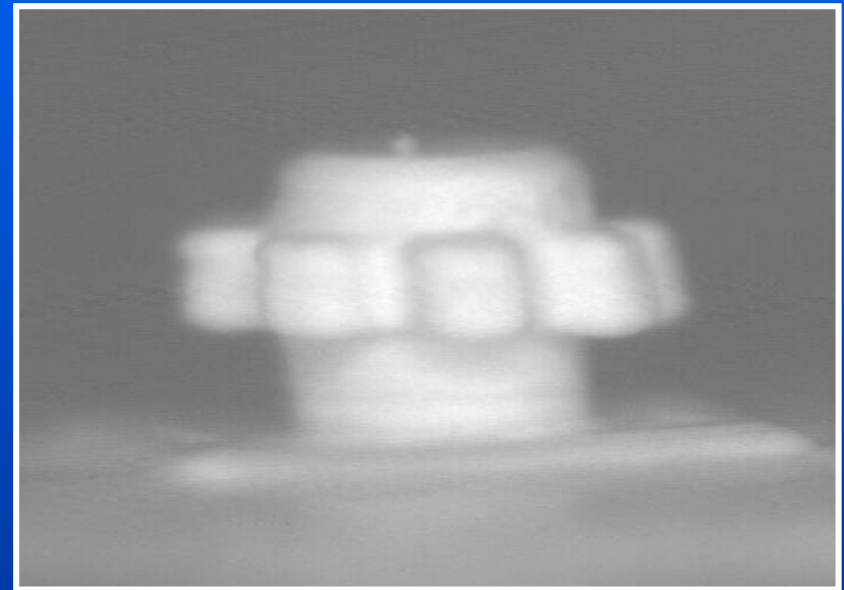
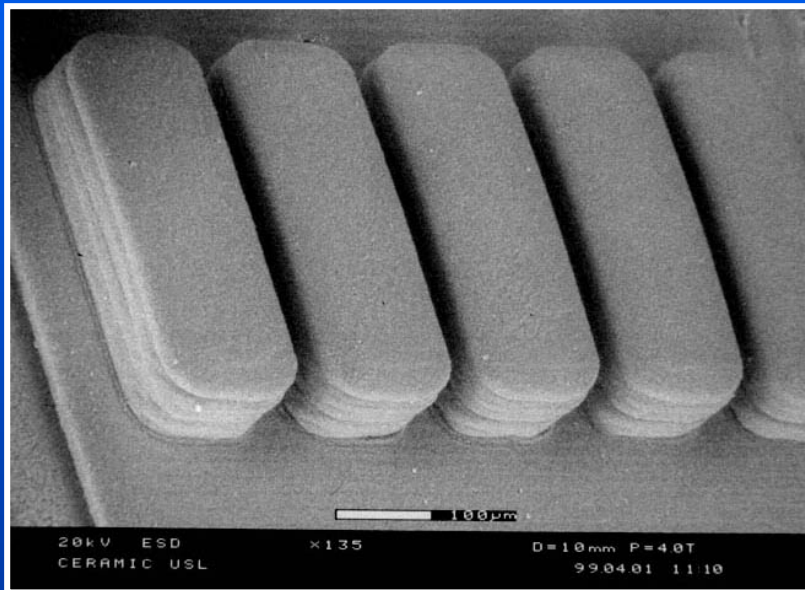
$$P_a = e^{-\epsilon \cdot l}$$

- Photo polymerization



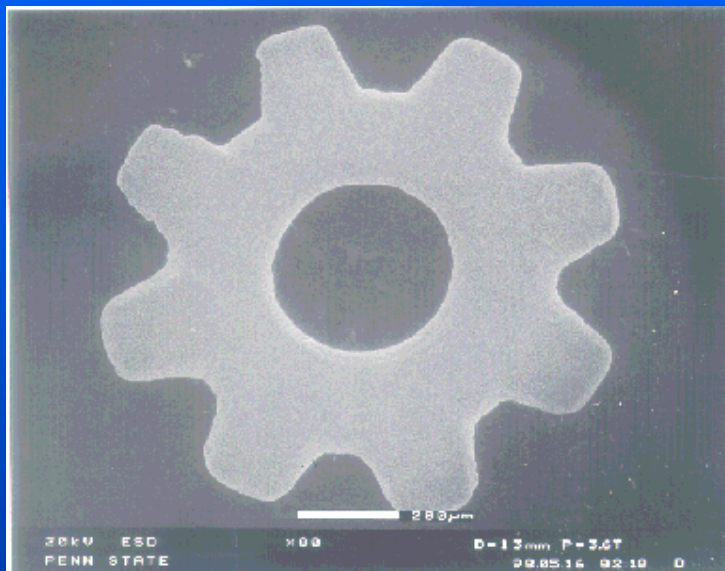
## 3D Ceramic $\mu$ SL

30  $\mu$ m Alumina Micro Channels    400  $\mu$ m Alumina Micro Gear

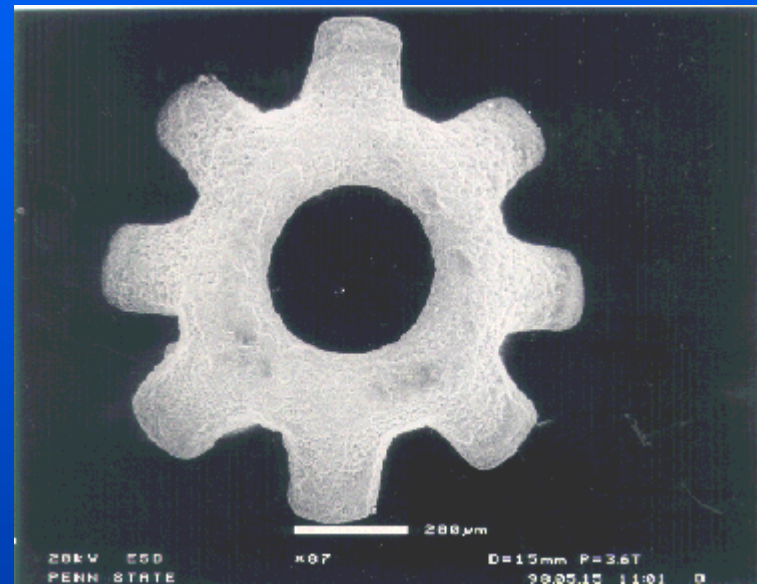


# Micro-Stereolithography of Ceramic Structures

- Green Alumina Gear

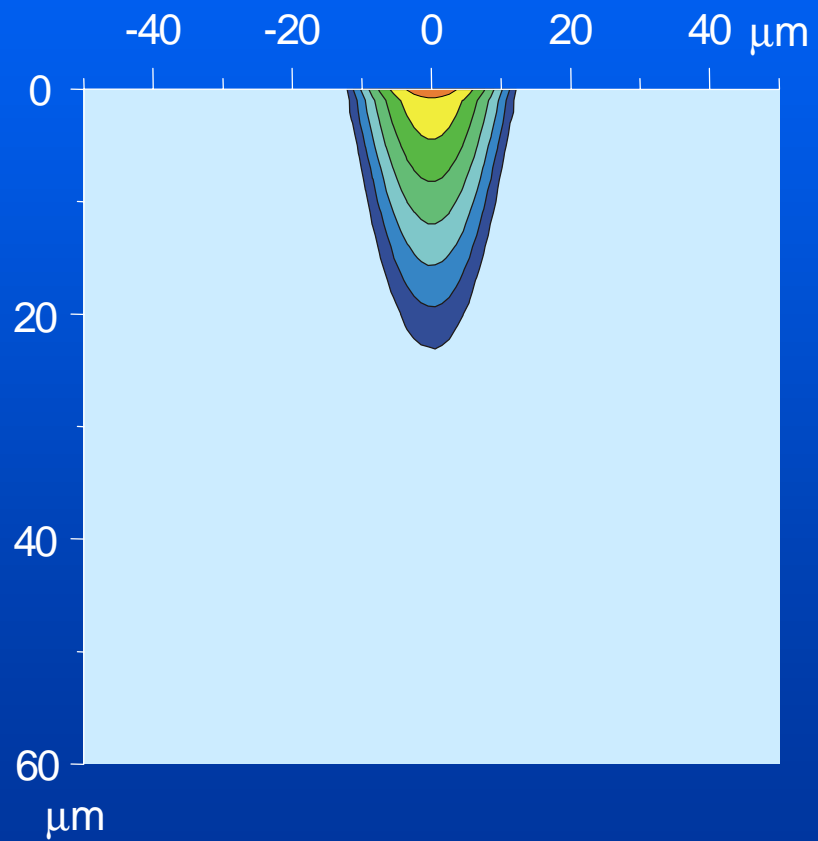


- Sintered Alumina Gear

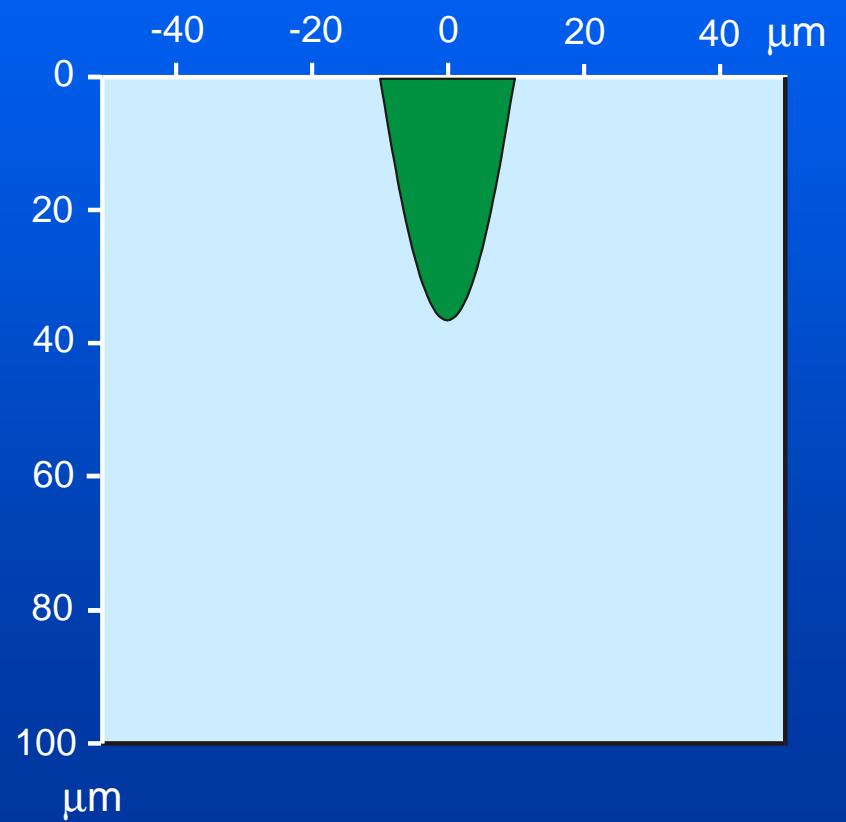


Sintered at 1400 °C and 3 hours  
Shrinkage due to sintering: 5-16%

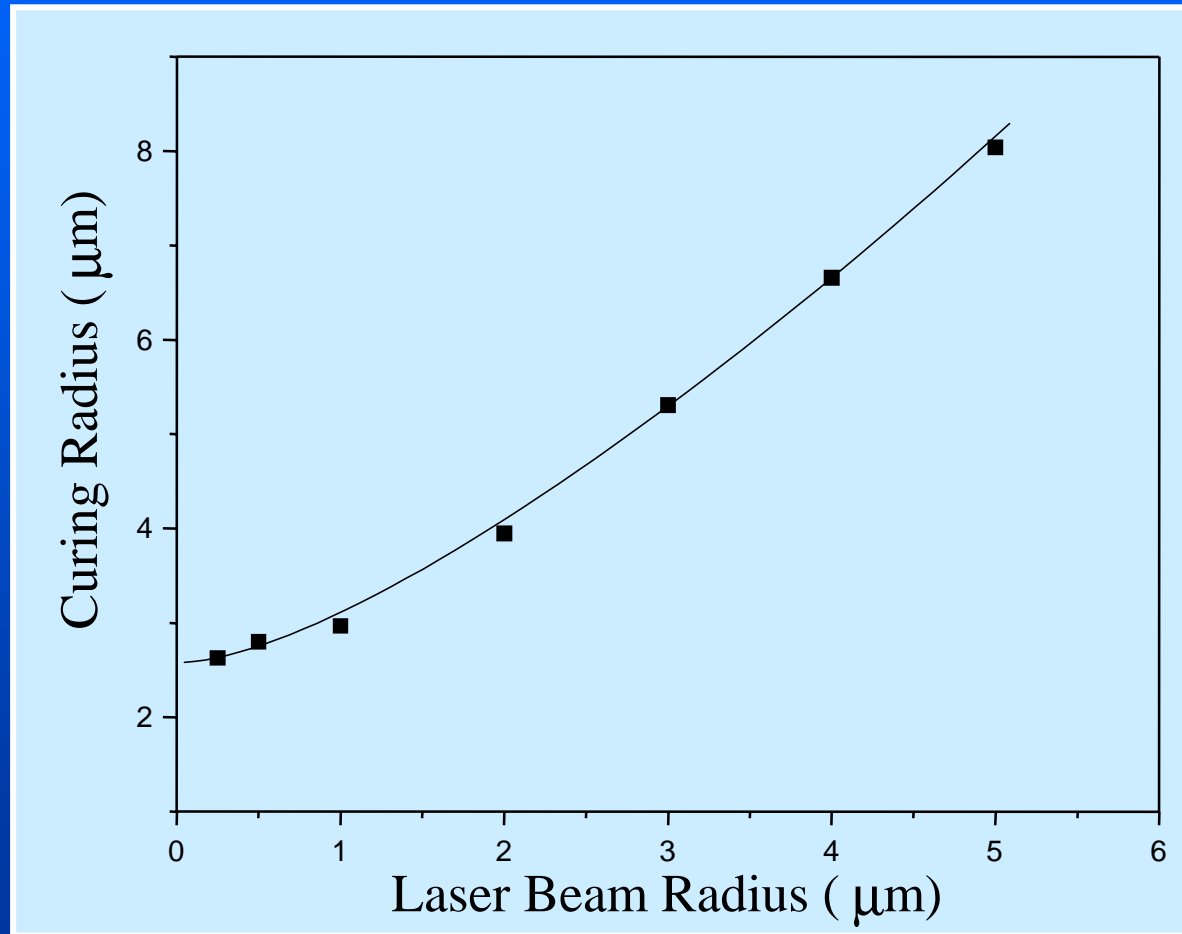
## Light Scattering



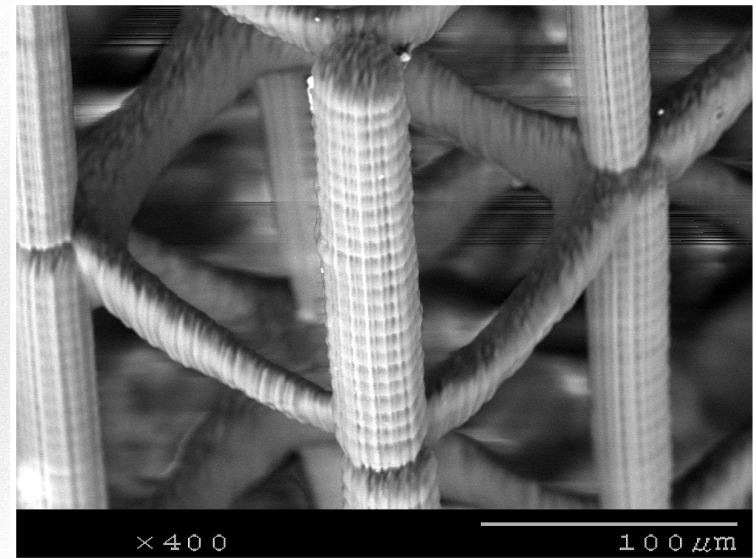
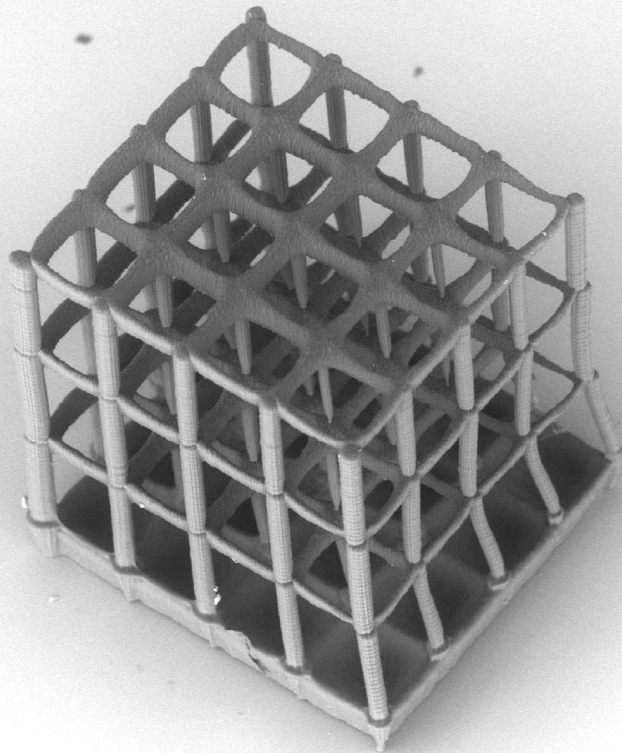
## Polymerization



## Lateral Resolution Limit in $\mu$ SL of Ceramics

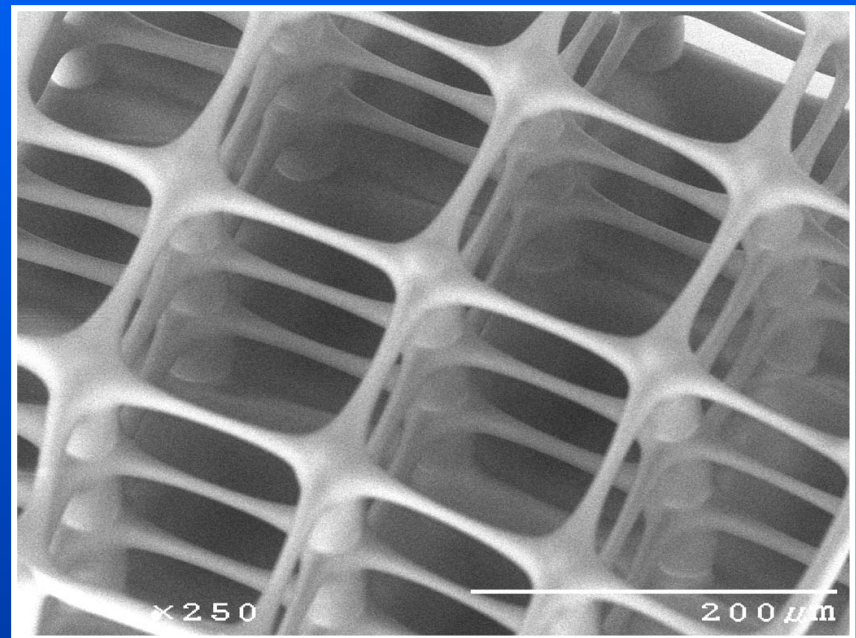
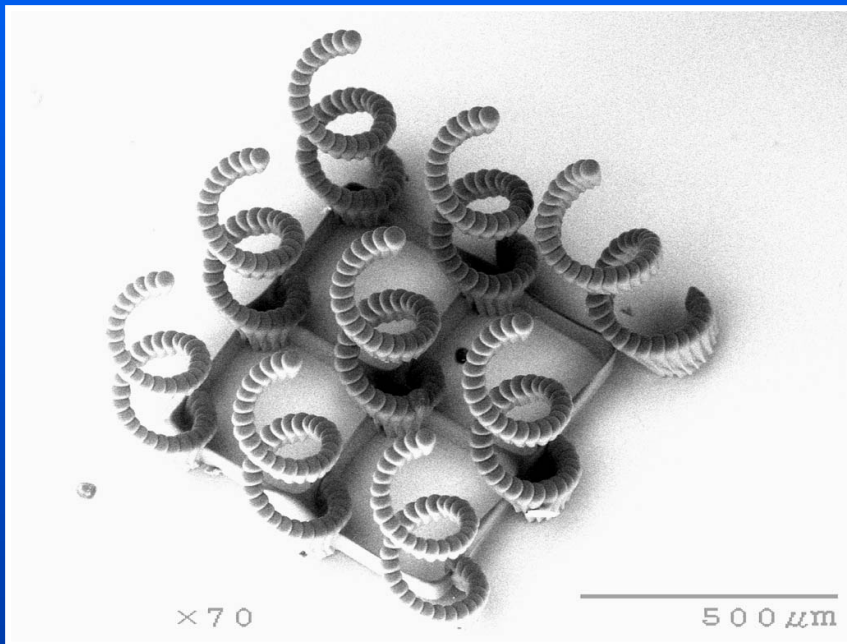


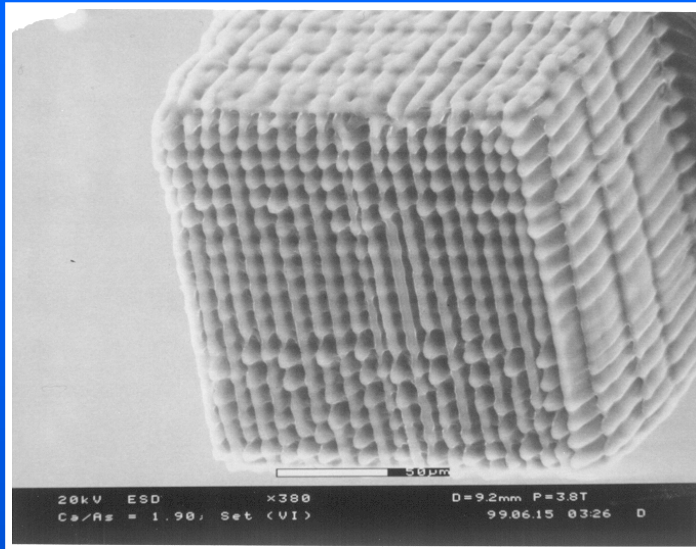
## 3D Matrix by DMD- $\mu$ SL



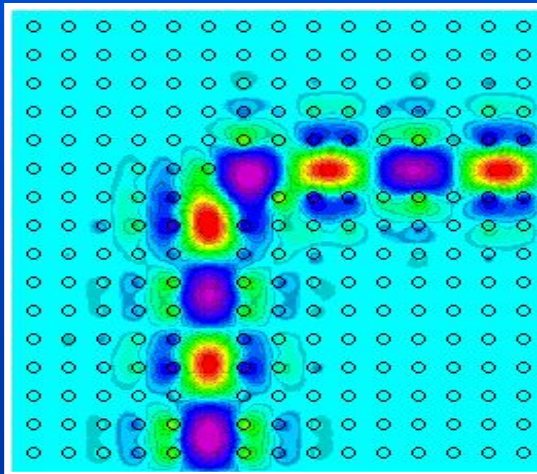


## 3D Coils Array and Micro-Matrix





(Zhang, 1999)



(Joannopoulos, 1996)

## 3D Photonic Band-gap Crystals

- Transmit/forbid light beam of selected wavelength (12 dB)
- Defects are pre-designed by CAD and embedded into the PBG by micro-stereolithography (decide what type defects and where they located, which is impossible in atomic scale defects in semiconductor)

## Applications

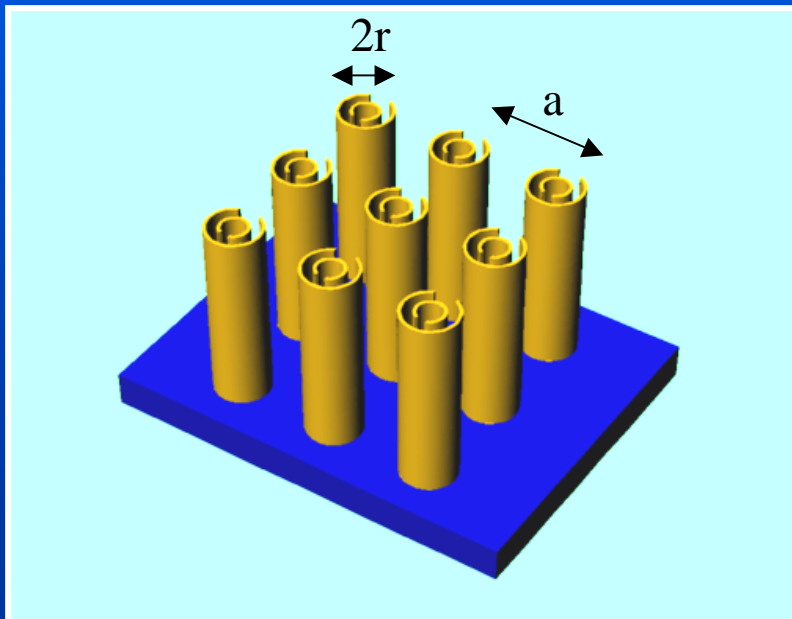
- Loss-free optical fiber
- High efficiency visible –IR bandpass filter/waveguide
- Resonant cavity in solid state laser



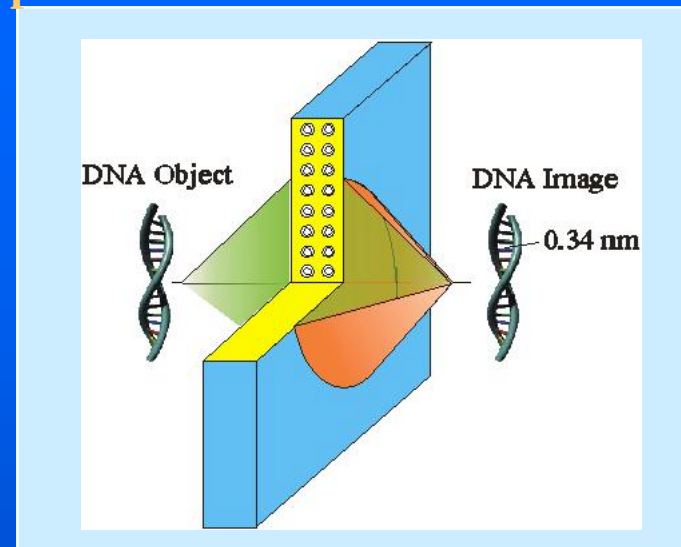
# Artificial Materials With Unprecedented Properties

(Theoretical work of John Pendry, 2000)

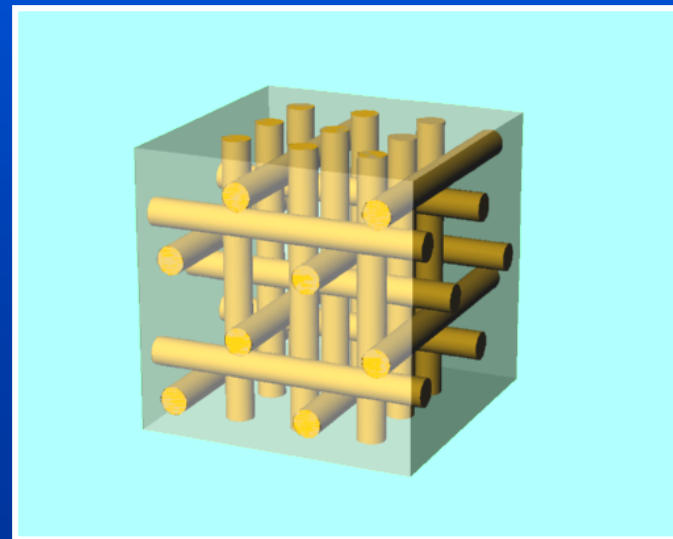
## Artificial Magnetism at High $f$



## Super-lens

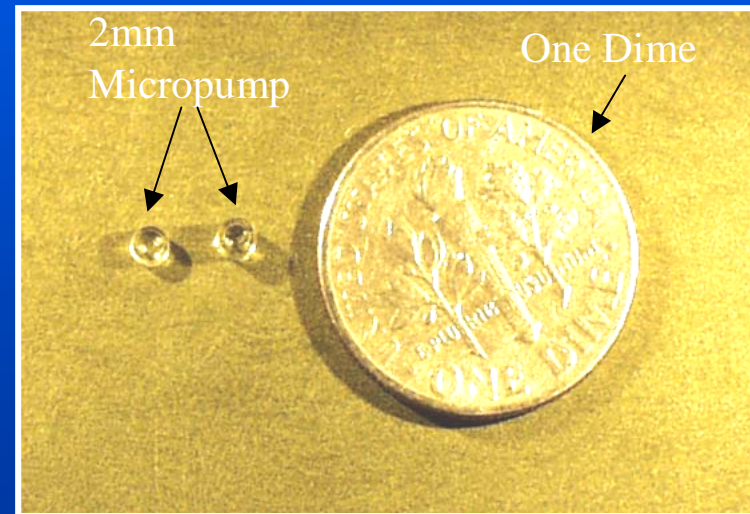
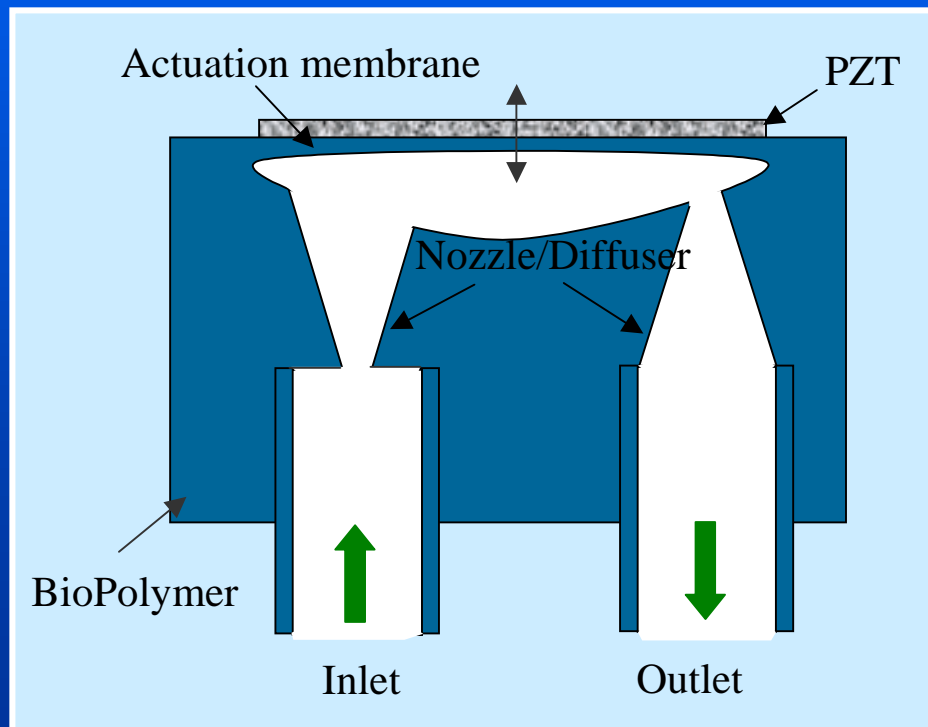


## Artificial Plasma



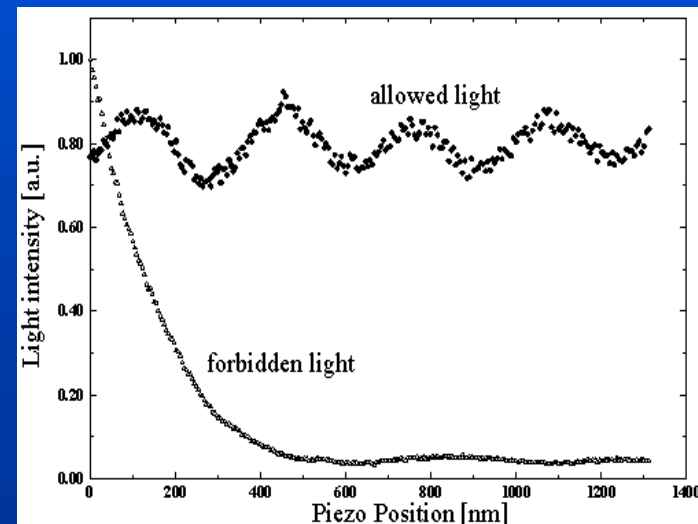
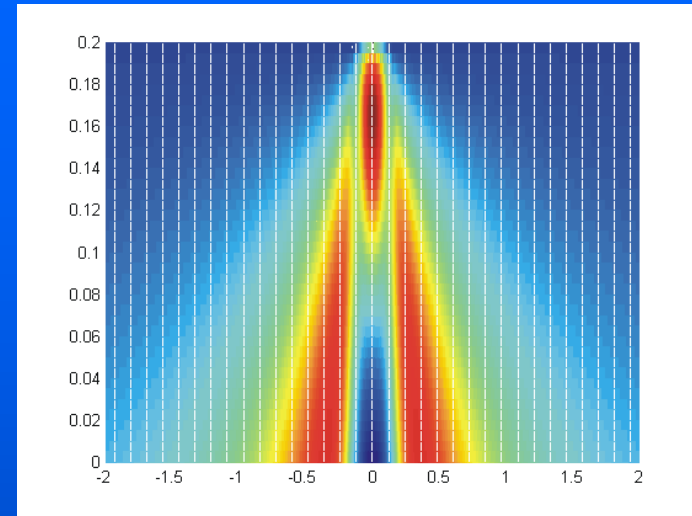
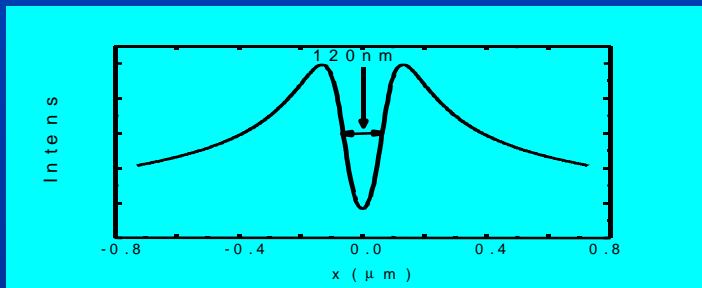
## 3D Valveless Micropump

- Truly 3D cavity structure to optimize the design
- High reliability due to no movable valves
- A wide variety of materials (eg. Bio-polymer)



# Near Field Optical nanolithography(NSOL)

- Near field scanning optical microscopy (NSOM)- a proven technology to break the diffraction limit.
- 2D nanopatterning with NSOM demonstrated features with  $\sim 100\text{nm}$  lateral resolution
- Computer simulation propose that NSOM has the potential in 3D nanolithography



## Conclusions

- Scanning micro-stereolithography has been developed
- Micro-stereolithography of complex 3D micro-structures has been demonstrated; For the first time,  $\mu$ SL of ceramic micro-structures has been succeeded
- Theoretical Simulation of micro-stereolithography shows good agreements with preliminary experimental results
- The unique 3D techniques enable exciting applications in photonics, bioMEMS and possibly novel thermally engineered materials.